


**• General Description**

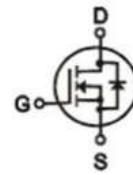
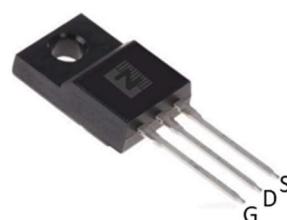
The ZM040N06F combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

**• Features**

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

**• Application**

- SMPS 2<sup>nd</sup> Synchronous Rectifier
- BLDC Motor driver

**• Product Summary**

 $V_{DS}=60V$ 
 $R_{DS(ON)}=4m\Omega$ 
 $I_D=120A$ 


TO-220F

**• Ordering Information:**

Part NO.	ZM040N06F
Marking	CA053N06SL
Packing Information	Bulk Tube
Basic ordering unit (pcs)	1000

**• Absolute Maximum Ratings ( $T_c = 25^\circ C$ )**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current( $TC=25^\circ C$ )	$I_D@TC=25^\circ C$	120	A
	$I_D@TC=75^\circ C$	91.2	A
	$I_D@TC=100^\circ C$	75.6	A
Pulsed Drain Current <sup>①</sup>	$I_{DM}$	250	A
Total Power Dissipation( $TC=25^\circ C$ )	$P_D@TC=25^\circ C$	85	W
Total Power Dissipation( $TA=25^\circ C$ )	$P_D@TA=25^\circ C$	3	W
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ C$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ C$



## •Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	1.47	° C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	42	° C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	° C

## •Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60			V
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2		2.5	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V			1.0	uA
Gate- Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V ,V <sub>DS</sub> =0V			±100	nA
Static Drain-source On Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =16A		4	6	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A		5.5	8	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =25V, I <sub>D</sub> =15A		32		s
Source-drain voltage	V <sub>SD</sub>	I <sub>S</sub> =16A			1.28	V

## •Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C <sub>iss</sub>	f = 1MHz V <sub>DS</sub> =25V	-	6510	-	pF
Output capacitance	C <sub>oss</sub>		-	450	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	200	-	

•Gate Charge characteristics(T<sub>a</sub> = 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q <sub>g</sub>	V <sub>DD</sub> = 25V I <sub>D</sub> = 25A V <sub>GS</sub> = 10V	-	54	-	nC
Gate - Source charge	Q <sub>gs</sub>		-	18	-	
Gate - Drain charge	Q <sub>gd</sub>		-	21	-	

Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;



Fig.1 Gate-Charge Characteristics

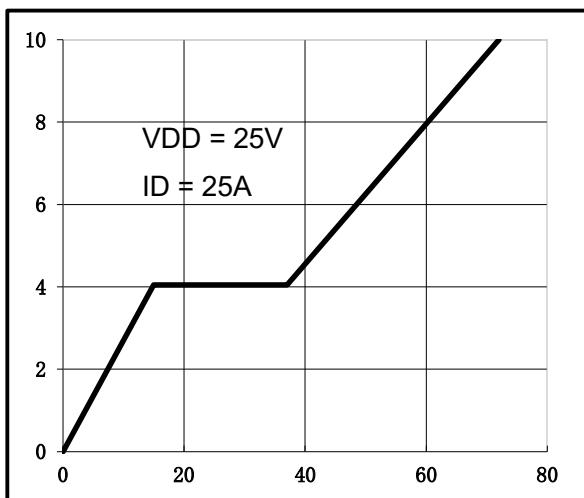


Fig.2 Capacitance Characteristics

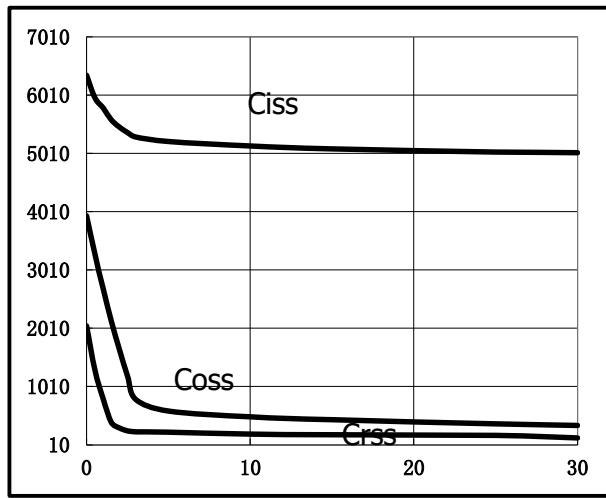


Fig.3 Power Dissipation

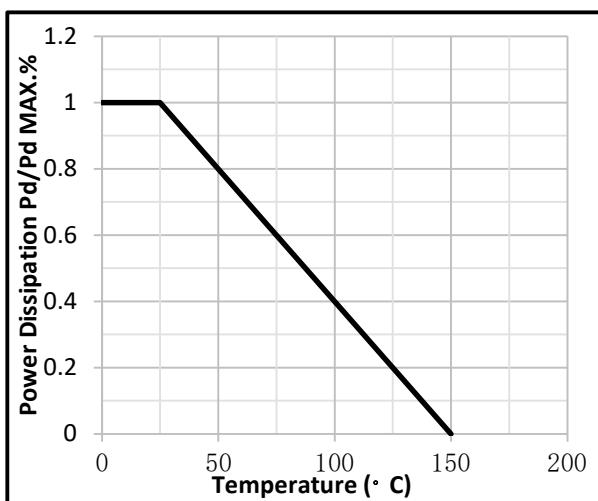


Fig.4 Typical output Characteristics

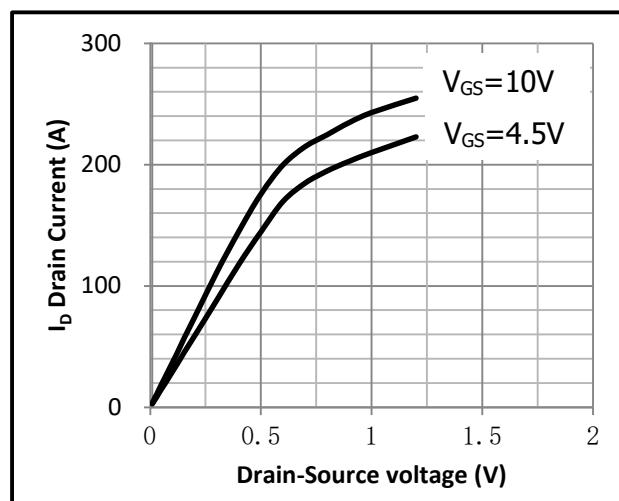


Fig.5 Threshold Voltage V.S Junction Temperature

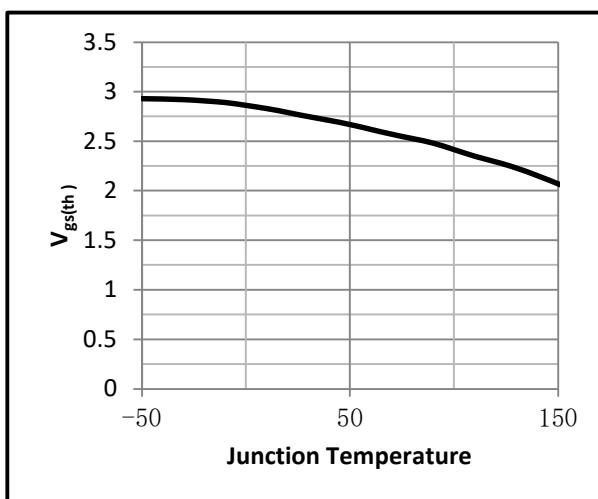


Fig.6 Resistance V.S Drain Current

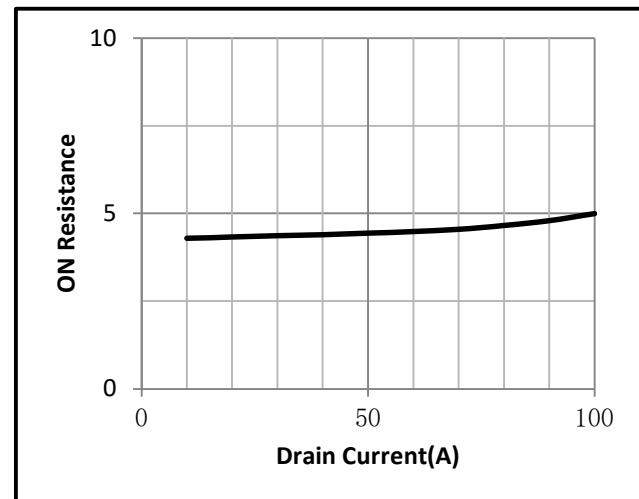




Fig.7 On-Resistance VS Gate Source Voltage

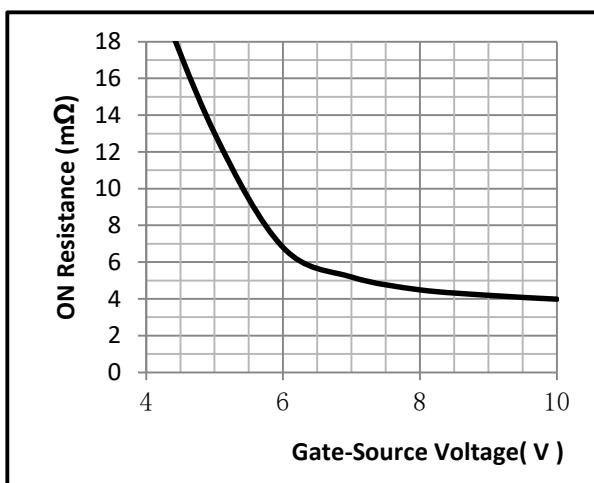


Fig.8 On-Resistance V.S Junction Temperature

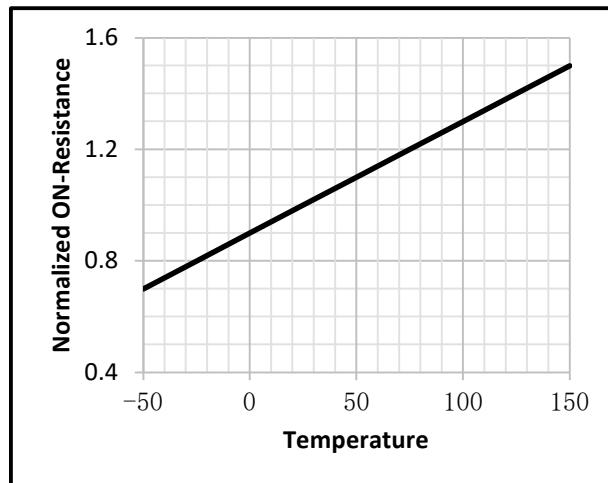


Fig.9 Switching Time Measurement Circuit

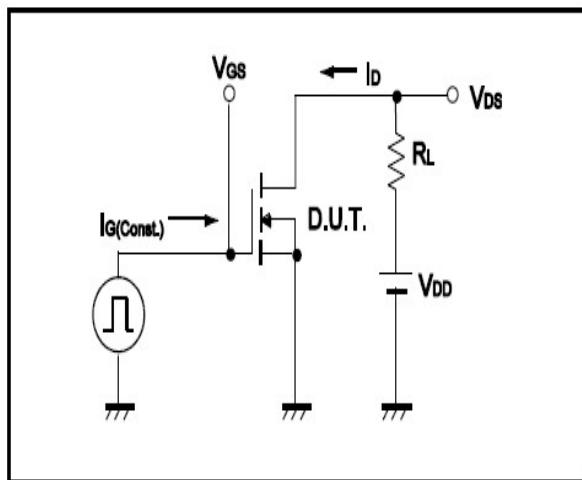


Fig.10 Gate Charge Waveform

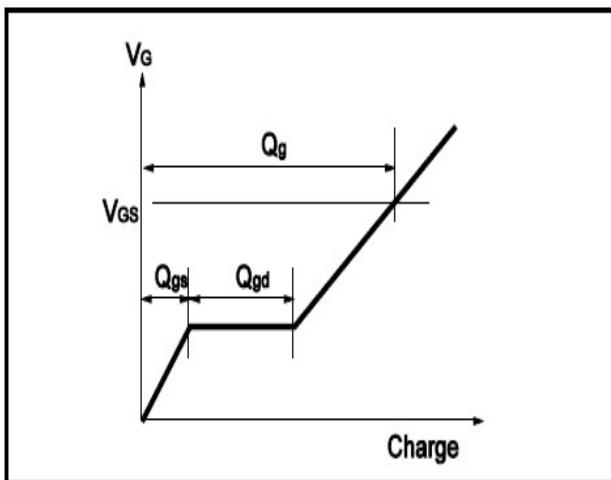


Fig.11 Switching Time Measurement Circuit

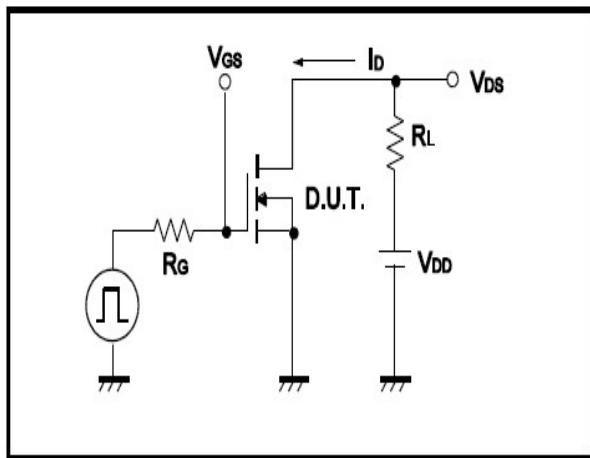
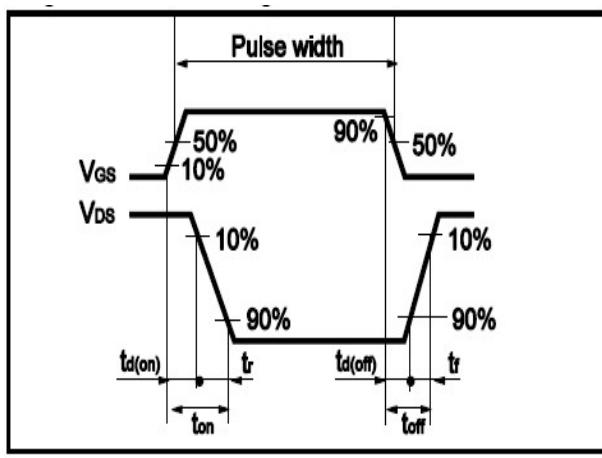


Fig.12 Gate Charge Waveform



**•Dimensions (TO-220F)**

Unit: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
C	4.5	4.9	b1	2.90	3.90
C	0.4	0.6	a	1.08	1.48
A	9.96	10.36	a1	0.70	0.90
B	15.67	16.07	E	2.34	2.74
B1	3.30	3.50	E1	2.34	2.74
R	3.08	3.28	C1	2.34	2.74
b	12.48	13.48	C2	2.56	2.96

